

PACKAGE STRUCTURE

ABSTRACT OF THE DISCLOSURE

A package structure includes a first insulation layer, at least one first electronic component, and a first re-distribution layer. The first electronic component is embedded within the first insulation layer, and the first electronic component includes plural first conducting terminals disposed on a bottom surface of the first electronic component. At least part of the bottom surface of the first electronic component is exposed from a bottom surface of the first insulation layer. The first re-distribution layer is formed on the bottom surface of the first insulation layer and contacted with the corresponding first conducting terminals.

[Figure 1]